

**Table I-5 to Subpart I of Part 98—Default Emission Factors (1-U<sub>ij</sub>) for Gas Utilization Rates (U<sub>ij</sub>) and By-Product Formation Rates (B<sub>ijk</sub>) for MEMS Manufacturing**

Process type factors	Process gas i											
	CF <sub>4</sub>	C <sub>2</sub> F <sub>6</sub>	CHF <sub>3</sub>	CH <sub>2</sub> F <sub>2</sub>	C <sub>3</sub> F <sub>8</sub>	c-C <sub>4</sub> F <sub>8</sub>	Remote NF <sub>3</sub>	NF <sub>3</sub>	SF <sub>6</sub>	C <sub>4</sub> F <sub>6a</sub>	C <sub>5</sub> F <sub>8a</sub>	C <sub>4</sub> F <sub>8O<sub>a</sub></sub>
	*	*	*	*	*	*	*					
CVD Chamber Cleaning 1-U <sub>i</sub>	0.9	0.6	NA	NA	0.4	0.1	0.02	0.2	NA	NA	0.1	0.1
CVD Chamber Cleaning BCF <sub>4</sub>	NA	0.1	NA	NA	0.1	0.1	<sup>2</sup> 0.02	<sup>2</sup> 0.1	NA	NA	0.1	0.1
CVD Chamber Cleaning BC <sub>3</sub> F <sub>8</sub>	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA	0.4

**Notes:** NA = Not applicable; i.e., there are no applicable default emission factor measurements for this gas. This does not necessarily imply that a particular gas is not used in or emitted from a particular process sub-type or process type.

<sup>1</sup> Estimate includes multi-gas etch processes.

<sup>2</sup> Estimate reflects presence of low-k, carbide and multi-gas etch processes that may contain a C-containing fluorinated GHG additive.